Docket No.

197211US2

IN RE APPLICATION OF:

Youichi TOBITA

SERIAL NO:

09/664,361

FILED:

September 18, 2000

FOR:

MULTILAYERED WIRING SUBSTRATE

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

- No additional fee is required
- Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- Additional documents filed herewith: Marked-up Copy; Letter Requesting Approval of Drawing Changes; Drawings (5 sheets)

The Fee has been calculated as shown below:

; CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS		RATE		CALCULATIONS
TOTAL	11	MINUS	20	0	х	\$18	=	\$0.00
INDEPENDENT	2	MINUS	3	0	х	\$84	=	\$0.00
		☐ MULTIPL	MULTIPLE DEPENDENT CLAIMS			\$280	=	\$0.00
		TOTAL OF ABOVE CALCULATIONS Reduction by 50% for filing by Small Entity						\$0.00
								\$0.00
		☐ Recordation of Assignment +				\$40	_	\$0.00
						TOT	AL ,	\$0.00

☐ A check in the amount of \$0.00 is attached.

- Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

22850

Customer Number 22850 Tel. (703) 413-3000 Fax. (703) 413-2220 (OSMMN 10/01) I:\atty\Rff\0057\197211\197211-ame-cvr.doc

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Gregory J. Maier

Registration No.

Surinder Sachar

Registration No. 34,423



197211US2

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

YOUICHI TOBITA

: EXAMINER: ALCALA, JOSE H.

SERIAL NO.: 09/664,361

FILED: SEPTEMBER 18, 2000

: GROUP ART UNIT: 2827

FOR: MULTILAYERED WIRING

SUBSTRATE

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated October 3, 2002, please amend this application as follows:

IN THE CLAIMS

Please amend Claim 1 as shown in clean form below. A marked-up copy of the amended claim is attached.

1. (Amended) A multilayered wiring substrate, comprising:

a plurality of multilayered wiring layers, at least one of said multilayered wiring layers comprising a signal wiring group made by a plurality of signal wirings disposed in parallel with one another; and

1

1 5/A 1 15/03